

Molex Japan Co.,Ltd.		Product Specification		P/No.: 1625-NP,NP1/NR,NR1	
	Item	Test Condition		Requirement	
3-4	Solderability	Soldering time : 3 ± 0.5 sec. Soldering pot : 230 ± 5 °C		Min. 3/4 of immersed area	
3-5	Resistance to soldering heat	Soldering time : 5 ± 0.5 sec. Soldering pot : 260 ± 5 °C		No damage	
3-6	Heat resistance	85 ± 2 °C, 96 hours	Contact resistance	20 mΩ max.	
			Appearance	No damage	
3-7	Humidity	Temperature : 40 ± 2 °C Relative Humidity: 90~95% Duration : 96 hours Measurement must be taken within 30 minute after tested	Contact resistance	20 mΩ max.	
			Dielectric strength	To pass para 1-3	
			Insulation resistance	100 MΩ min.	
			Appearance	No damage	
3-8	Temperature cycling (5 cycles)	One cycle consists of (1) -55 ± 3 °C, 30 minute (2) Room temp. 10~15 minute (3) 105 ± 2 °C, 30 minute (4) Room temp. 10~15 minute	Contact resistance	20 mΩ max.	
			Appearance	No damage	
3-9	Salt Spray	Temperature: 35 ± 2 °C Solution : $5 \pm 1\%$ Spray time : 48 ± 4 hours Measurement must be taken after water rinse.	Contact resistance	20 mΩ max.	
			Appearance	No significant corrosion	
3-10	SO ₂ Gas	24 hours in sulfur dioxide gas (SO ₂) 50 ± 5 ppm at 40 ± 2 °C	Contact resistance	20 mΩ max.	

4. Terminal To Be Used

	Customer P/No	Molex P/No	Wire Size	Insulation Dia.
1.		1560,1561	AWG #18 ~ #24	φ (1.5) ~ 3.1
2.		1854,1855	AWG #22 ~ #28	φ (1.1) ~ 1.5
3.		1778,1779	-----	-----
4.				

5. Ambient Temperature Range : -40 °C ~ 105 °C

6. Construction,Dimension and Material : Specified by the attached drawing.

REV. B

7. Insertion and Extraction Force

No of Ckt.	Insertion Force (kgf, max.)			Extraction Force (kgf, min.)		
	1st	6th	30th	1st	6th	30th
1	5.0	4.5	4.5	0.8	0.5	0.5
2	7.0	6.0	6.0	1.5	1.0	1.0
3	10.0	9.0	8.0	1.8	1.2	1.2
4	13.0	12.0	10.0	2.0	1.4	1.4
5	15.5	14.0	11.0	2.3	1.5	1.5
6	18.0	16.0	12.0	2.5	1.6	1.6
9	26.0	23.0	17.0	3.5	2.5	2.5
12	34.0	30.0	23.0	4.5	3.5	3.5
15	40.0	35.0	30.0	5.5	4.5	4.5
24	60.0	55.0	50.0	6.5	5.5	5.5

REV. B